



LESD8D12AT5G ESD PROTECTION DIODE

Discription

The LESD8D12AT5G is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

Applications

- I Cellular phones audio
- I MP3 players
- I Digital cameras
- I Portable applicationss
- I mobile telephone

Features

- | Low Leakage
- I Response Time is Typically < 1 ns
- I ESD Rating of Class 3 (> 16 kV) per Human Bo dy Model
- I IEC61000-4-2 Level 4 ESD Protection
- I We declare that the material of product compliance with RoHS requirements.



LESD8D12AT5G



Ordering information

Device	Marking	Shipping	
LESD8D12AT5G	HA	10000/Tape&Reel	

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air Contact Contact discharge		±15 ±8	kV kV
ESD Voltage Per Human Body Model		16	kV
Total Power Dissipation on FR-5 Board (Note 1)	PD	200	Mw
@ T _A =25℃			
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	°C
Lead Solder Temperature – Maximum (10	TL	260	°C
Second Duration)			

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.



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ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
Ι _Τ	Test Current
I _F	Forward Current
V _F	Forward Voltage @ I _F
P _{pk}	Peak Power Dissipation
С	Max. Capacitance @V _R = 0 and f = 1 MHz



Uni-Directional TVS

ELECTRICAL CHARACTERISTICS (T_=25 °C unless otherwise noted)

	V _{RWM}	I _R	V _{BR}	Ι _Τ	I _{PP}	Vc	P _{PK}	С
	(V)	(µA)	(V)	(mA)	(A)	(V)	(W)	(pF)
Device		@	@ I _T			@ Max I _{PP}	(8*20 µs)	
		V_{RWM}	(Note 2)		(Note 3)	(Note 3)		
	Max	Max	Min		Max	Max	Max	Тур
LESD8D12AT5G	12	1.0	13.3	1.0	4	20	80	20

2. V_{BR} is measured with a pulse test current IT at an ambient temperature of $25^\circ\!\mathrm{C}$

3. Surge current waveform per Figure 3.



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Fig 2. Negative 8kV contact per IEC 61000-4-2- LESD8D12AT5G



Figure 3. 8*20 µs Pulse Waveform



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OUTLINE AND DIMENSIONS



S0D882					
Dim	Min	Тур	Max		
D	0.95	1.00	1.05		
Е	0.55	0.60	0.65		
е	-	0.64	-		
L	0.44	0.49	0.54		
b	0.20	0.25	0.30		
А	0.43	0.48	0.53		
A1	0	-	0.05		
A3	0.127REF.				
All Dimensions in mm					



SOLDERING FOOTPRINT

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Dimensions	(mm)
с	0.70
G	0.30
Х	0.40
X1	1.10
Y	0.70

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